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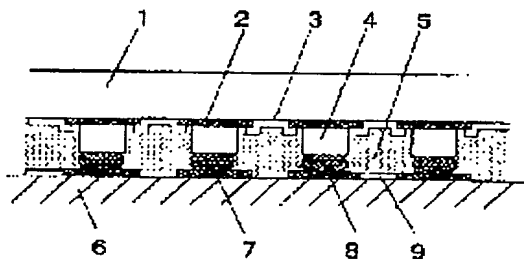
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## (54) SEMICONDUCTOR DEVICE AND ITS MANUFACTURING METHOD

## (57)Abstract:

PROBLEM TO BE SOLVED: To obtain a semiconductor device in which damage due to the mounting load on a member constituting the semiconductor device is lessened and the semiconductor device is connected electrically with a circuit board more reliably and stably.

SOLUTION: In the semiconductor device, the semiconductor device 1 is connected electrically with the circuit board 6 through a stress relaxing layer 8 composed of a highly elastic and conductive material, and electrical connection is made under a state where the stress relaxing layer 8 is compressed. Since the stress relaxing layer composed of a highly elastic and conductive material can absorb variation in the height of bump electrodes or the flatness of the circuit board easily, mounting load can be reduced as compared with conventional case and damage on a member constituting the semiconductor device is lessened. Since the stress relaxing layer is secured under compressed state, relaxation due to aging of sealing resin has an allowance and shearing stress also has an allowance thus ensuring a high connection quality.



## LEGAL STATUS

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